

SOT2014-1

SIL5, single in-line package, 5 terminals, 1.27 mm pitch, 8.0 mm x 4.65 mm x 2.65 mm body

23 April 2019

Package information

1 Package summary

| | |
|---------------------------------------|------------------------------|
| Terminal position code | B (bottom) |
| Package type descriptive code | SIL5 |
| Package style descriptive code | SIP (single in-line package) |
| Mounting method type | T (through-hole mount) |
| Issue date | 01-04-2019 |
| Manufacturer package code | 98ASA01322D |

Table 1. Package summary

| Parameter | Min | Nom | Max | Unit |
|--------------------------------|-----|------|-----|------|
| package length | - | 8 | - | mm |
| package width | - | 4.65 | - | mm |
| package height | - | 2.65 | - | mm |
| nominal pitch | - | 1.27 | - | mm |
| actual quantity of termination | - | 5 | - | |



SIL5, single in-line package, 5 terminals, 1.27 mm pitch, 8.0 mm x 4.65 mm x 2.65 mm body

2 Package outline

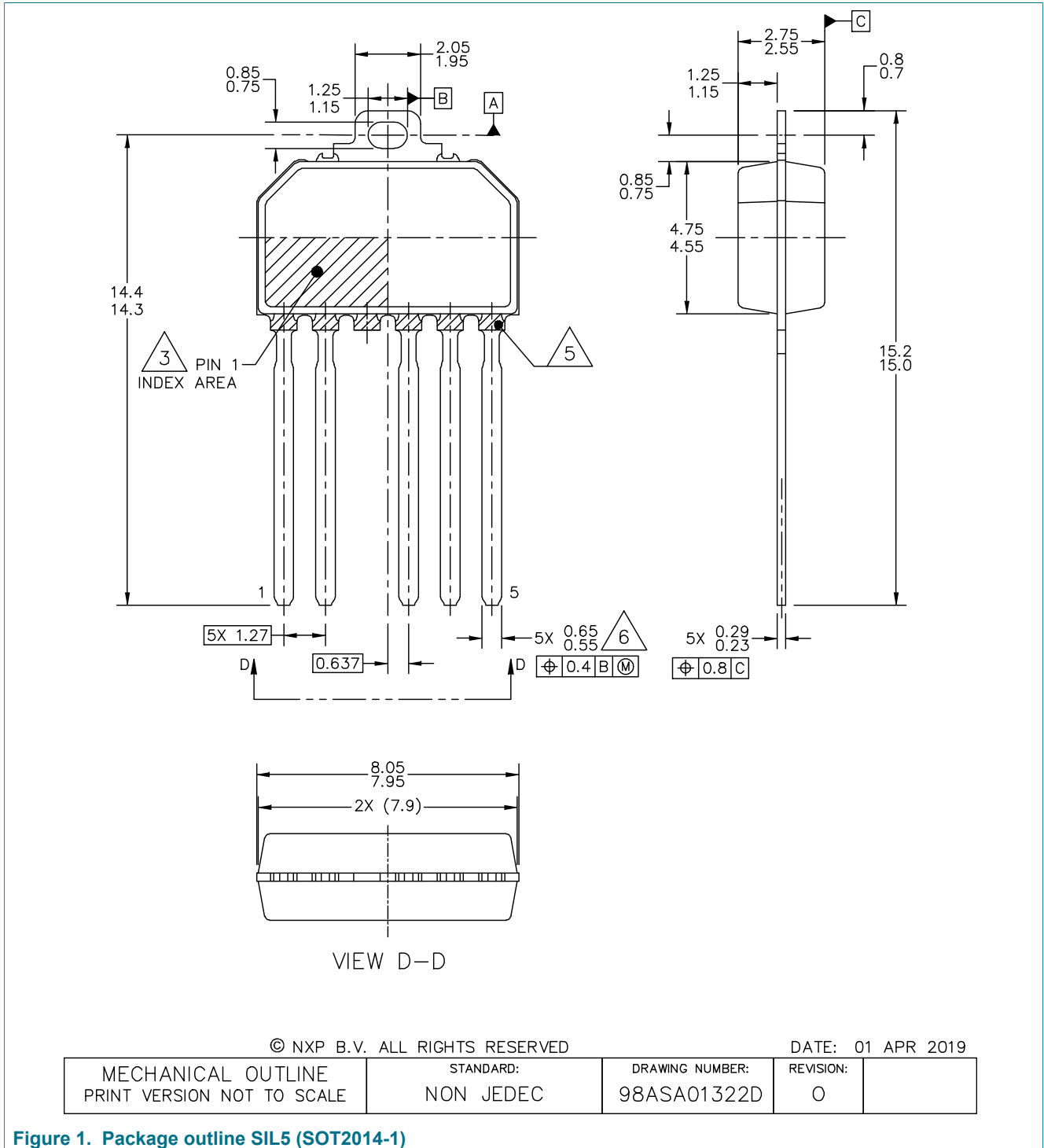





Figure 1. Package outline SIL5 (SOT2014-1)

SIL5, single in-line package, 5 terminals, 1.27 mm pitch, 8.0 mm x 4.65 mm x 2.65 mm body

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETER.
2. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M-1994.
3.  PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. PACKAGE BODY SIZE DOES NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.15 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
5.  HATCHED AREA REPRESENT ALLOWABLE MOLD FLASH OF 0.5 MAX.
6.  LEAD SHOULDER DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.15 TOTAL IN EXCESS OF THE LEAD SHOULDER AT MAXIMUM MATERIAL CONDITION.

© NXP B.V. ALL RIGHTS RESERVED

DATE: 01 APR 2019

| | | | | |
|--|------------------------|--------------------------------|----------------|--|
| MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE | STANDARD: NON JEDEC | DRAWING NUMBER: 98ASA01322D | REVISION: 0 | |
|--|------------------------|--------------------------------|----------------|--|

Figure 2. Package outline note SIL5 (SOT2014-1)

3 Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Contents

1 Package summary1
2 Package outline2
3 Legal information4